

## Optocoupler, Phototransistor Output, With Base Connection

### Features

- Interfaces with common logic families
- Input-output coupling capacitance < 0.5 pF
- Industry Standard Dual-in line 6-pin package
- 5300 V<sub>RMS</sub> isolation test voltage

### Agency Approvals

- UL - File No. E52744 System Code H or J
- DIN EN 60747-5-2(VDE0884)  
DIN EN 60747-5-5 pending  
Available with Option 1
- CSA 93751
- BSI IEC60950 IEC60965

### Applications

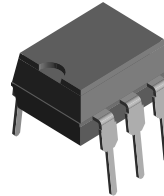
AC mains detection  
 Reed relay driving  
 Switch mode power supply feedback  
 Telephone ring detection  
 Logic ground isolation  
 Logic coupling with high frequency noise rejection  
 For additional design information see Application Note 45

### Description

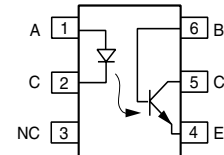
The MCT27x family is an Industry Standard Single Channel Phototransistor Couplers. It includes the MCT270/ 271/ 272/ 273/ 274/ 275/ 276/ 277 couplers. Each optocoupler consists of gallium arsenide infrared LED and a silicon NPN phototransistor.

These couplers are Underwriters Laboratories (UL) listed to comply with a 5300 V<sub>RMS</sub> isolation test voltage.

This isolation performance is accomplished through Vishay double molding isolation manufacturing process. Compliance to DIN EN 60747-5-2(VDE0884)/ DIN EN 60747-5-5 pending partial discharge isolation specification is available by ordering option 1.



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These isolation processes and the Vishay ISO9001 quality program results in the highest isolation performance available for a commercial plastic phototransistor optocoupler.

The devices are available also in lead formed configuration suitable for surface mounting and are available either on tape and reel, or in standard tube shipping containers.

### Order Information

Part	Remarks
MCT270	CTR > 50 %, DIP-6
MCT271	CTR 45 - 90 %, DIP-6
MCT272	CTR 75 - 150 %, DIP-6
MCT273	CTR 125 - 250 %, DIP-6
MCT274	CTR 225 - 400 %, DIP-6
MCT275	CTR 70 - 210 %, DIP-6
MCT276	CTR 15 - 60 %, DIP-6
MCT277	CTR > 100 %, DIP-6
MCT270-X009	CTR > 50 %, SMD-6 (option 9)
MCT277-X009	CTR > 100 %, SMD-6 (option 9)

For additional information on the available options refer to Option Information.

### Absolute Maximum Ratings

$T_{amb} = 25\text{ °C}$ , unless otherwise specified

Stresses in excess of the absolute Maximum Ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute Maximum Rating for extended periods of the time can adversely affect reliability.

### Input

Parameter	Test condition	Symbol	Value	Unit
Reverse voltage		$V_R$	6.0	V
Forward current		$I_F$	60	mA
Surge current	$t < 10\ \mu\text{s}$	$I_{FSM}$	2.5	A
Power dissipation		$P_{diss}$	100	mW

### Output

Parameter	Test condition	Symbol	Value	Unit
Collector-emitter breakdown voltage		$V_{CEO}$	70	V
Emitter-base breakdown voltage			7.0	V
Collector current		$I_C$	50	mA
	$t < 1.0\ \text{ms}$	$I_C$	100	mA
Power dissipation		$P_{diss}$	150	mW

### Coupler

Parameter	Test condition	Symbol	Value	Unit
Isolation test voltage		$V_{ISO}$	5300	$V_{RMS}$
Creepage			$\geq 7.0$	mm
Clearance			$\geq 7.0$	mm
Isolation thickness between emitter and detector			$\geq 0.4$	mm
Comparative tracking index per DIN IEC 112/VDE0303, part 1			175	
Isolation resistance	$V_{IO} = 500\ \text{V}, T_{amb} = 25\text{ °C}$	$R_{IO}$	$10^{12}$	$\Omega$
	$V_{IO} = 500\ \text{V}, T_{amb} = 100\text{ °C}$	$R_{IO}$	$10^{11}$	$\Omega$
Storage temperature		$T_{amb}$	- 55 to + 150	$^{\circ}\text{C}$
Operating temperature		$T_{amb}$	- 55 to + 100	$^{\circ}\text{C}$
Junction temperature		$T_j$	100	$^{\circ}\text{C}$
Soldering temperature	max. 10 s dip soldering: distance to seating plane $\geq 1.5\text{mm}$	$T_{sld}$	260	$^{\circ}\text{C}$



## Electrical Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements.

### Input

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage	$I_F = 20\text{ mA}$	$V_F$			1.5	V
Reverse current	$V_R = 3.0\text{ V}$	$I_R$			10	$\mu\text{A}$
Capacitance	$V_R = 0, f = 1.0\text{ MHz}$	$C_O$		25		pF

### Output

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Collector-emitter breakdown voltage	$I_C = 10\text{ }\mu\text{A}, I_F = 0\text{ mA}$	$BV_{CEO}$	30			V
Emitter-collector breakdown voltage	$I_E = 10\text{ }\mu\text{A}, I_F = 0\text{ mA}$	$BV_{ECO}$	7.0			V
Collector-base breakdown voltage	$I_C = 10\text{ }\mu\text{A}, I_F = 0\text{ mA}$	$BV_{CBO}$	70			V
Collector-emitter leakage current	$V_{CE} = 10\text{ V}, I_F = 0\text{ mA}$	$I_{CEO}$			50	nA

### Coupler

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Resistance, input to output	$V_{IO} = 500\text{ VDC}$	$R_{IO}$		$10^{12}$		$\Omega$
Capacitance (input-output)		$C_{IO}$		0.5		pF
Collector-emitter saturation voltage	$I_{CE} = 2.0\text{ mA}, I_F = 16\text{ mA}$	$V_{CEsat}$			0.4	V

### Current Transfer Ratio

Parameter	Test condition	Part	Symbol	Min	Typ.	Max	Unit
DC Current Transfer Ratio	$V_{CE} = 10\text{ V}, I_F = 10\text{ mA}$	MCT270	$CTR_{DC}$	50			%
		MCT271	$CTR_{DC}$	45		90	%
		MCT272	$CTR_{DC}$	75		150	%
		MCT273	$CTR_{DC}$	125		250	%
		MCT274	$CTR_{DC}$	225		400	%
		MCT275	$CTR_{DC}$	70		210	%
		MCT276	$CTR_{DC}$	15		60	%
		MCT277	$CTR_{DC}$	100			%
Current Transfer Ratio (collector-emitter)	$V_{CE} = 0.4\text{ V}, I_F = 16\text{ mA}$	MCT271	$CTR_{CE}$	12.5			%
		MCT272	$CTR_{CE}$	12.5			%
		MCT273	$CTR_{CE}$	12.5			%
		MCT274	$CTR_{CE}$	12.5			%
		MCT275	$CTR_{CE}$	12.5			%
		MCT276	$CTR_{CE}$	12.5			%
		MCT277	$CTR_{CE}$	40			%